**Att. No. 1**

**ORDER DESCRIPTION**

1. **Object of the contract**

The subject of the order is the supply of semiconductors wafers listed below by name and quantity needed:

1. InP SI 2” SSP 75 pieces
2. InP SI 4” DSP 25 pieces
3. InP N 3” DSP 25 pieces
4. **Parameters**

|  |  |  |
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| Product name | Parametrer | Specification |
| **2” InP Semi Insulating****Doped with Fe** | Diameter 2” Thickness: 350±25 µmDiameter: (50.0 to 50.8)±(0.3 to 0.5mm) | Grade: | Prime, Epi-ready |
| Orientation: | (100)±0.3o |
| Primary Flat: | EJ (0-1-1) ±(0.5o do 1o) |
| Secondary Flat | EJ (0-11) ±(0.5o do 2o) |
| Resistivity: | >1E7 ohm cm |
| EPD (Average): | ≤5 000/cm2 max |
| Surface Finish: | SSP (single side polished) Side 1: Polished Side 2: Etched |
| Packaging: | ePAK, individual box, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room. |
| Product name | Parametrer | Specification |
| **4” InP Semi Insulating****Doped with Fe** | Diameter 4”Thickness: 625±25 µmDiameter: 100±0.4 mm | Grade: | Prime, Epi-ready |
| Orientation: | (100)±0.3o |
| Primary Flat: | EJ (0-1-1) ±(0.5o do 1o) |
| Secondary Flat | EJ (0-11) ±(0.5o do 2o) |
| Resistivity: | >1E7 ohm cm |
| EPD (Average): | ≤10 000/cm2 max |
| Surface Finish: | DSP (double side polished) Side 1: Polished Side 2: polished |
| Packaging: | ePAK, individual box, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room. |
| Product name | Parametrer | Specification |
| **3” InP N-type** **Doped with S** | Diameter 3”Thickness: (600 to 625)±25 µmDiameter: 76.2±(0.3 do 0.4mm) | Grade: | Prime, Epi-ready |
| Orientation: | (100)±0.3o |
| Primary Flat: | EJ (0-1-1) ±(0.5o do 1o) |
| Secondary Flat | EJ (0-11) ±(0.5o do 2o) |
| Carrier Conc.: | ≥ 1E18/cm3 |
| EPD (Average): | ≤5000/cm2 max |
| Surface Finish: | DSP (Double side polished) Side 1: Polished Side 2: Polished  |
| Packaging: | ePAK, individual box, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room. |